

1. parameters.

Item	Values
Material	FR-4,CEM-3,CEM-1.AL HDI
Min Solder Mask bridge	0.1mm
Min/max Solder Mask thickness	10um-25um
Min hold solder diameter	0.1mm(single side)
Diameter Tolerance	PTH $\pm 0.076\text{mm}$ NPTH $\pm 0.05\text{mm}$
Tenting by Mask (yes/no)	Yes
Layer Counts	1-12 LAYERS for
Board Thickness	0.4mm—3.5mm
Thickness Tolerance($t \geq 0.8\text{mm}$)	0.8 $\pm 0.1\text{mm}$; 1.2-1.6 $\pm 0.13\text{mm}$; 2.4 $\pm 0.18\text{mm}$; 3.2 $\pm 0.25\text{mm}$
Thickness Tolerance($T < 0.8\text{mm}$)	0.4-0.6 $\pm 0.1\text{mm}$
Minimum Line (0,5OZ)	0.10mm(for plating gold)
Minimum Space (0,5OZ)	0.10mm(for plating gold)
Minimum Line (1OZ)	0.15mm
Minimum Line (2OZ)	0.20mm
Minimum Line (3OZ)	0.25mm
Minimum Space (1OZ)	0.15mm
Minimum Space (2OZ)	0.20mm
Minimum Space (3OZ)	0.25mm
Out Layer Copper Thickness	0.5-4.0OZ
Inner Layer Copper Thickness	0.5-4.0OZ
Min Drilling Hole (Finished)	0.25mm
Annular ring	0.1mm
Registration	$\pm 0.1\text{mm}$

Aspect Ratio	Through Holes - 8:1
Solder Mask color	Green, black, red, white.
Mini. Solder Mask Clearance	0.05mm
Legend color	Green, white, red, yellow, black.
Maximum Board Size	500x600mm
Twist and Bow (for SMT assemble)	≤0.75%
Thickness Tin/Lead HASL	5-25um
Thickness Lead Free HASL	5-25um
OSP thickness	0.25-0.4um
Thickness Immersion Tin	0.8—1.2um
Thickness Immersion Gold	0.025um-0.2um
Thickness Gold Plating for Standart Flash Gold	0.025-0.076um
Thickness Gold Plating for Soft Gold	0.025-0.076um
Thickness Gold Plating for Hard Gold	0.25-0.76um
Thickness Ni Plating	3—5um